



**GP**  
**ELECTRONICS**

**GPT046N08WBT**

**85V N-Channel MOSFET**

### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}TYP$	$I_D$
80V	4.0mΩ@10V	140A

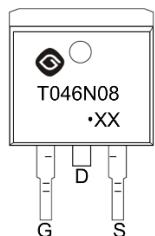
### Feature

- Shielded Gate Trench Technology
- Excellent  $R_{DS(ON)}$
- Low Gate Charge
- High Current
- Lead Free

### Application

- High Efficiency Power Supply
- Secondary Synchronous Rectifier

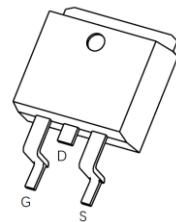
### MARKING:



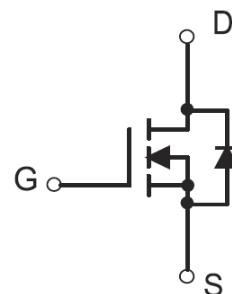
T046N08 = Device code

XX = Date Code

**TO-263-2L**



**Schematic diagram**



### ABSOLUTE MAXIMUM RATINGS ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	80	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1,2</sup>	$I_D$	140	A
Pulsed Drain Current	$I_{DM}$	280	A
Avalanche Current*	$I_{AS}$	28	A
Single Pulse Avalanche Energy*	$E_{AS}$	263	mJ
Maximum Power Dissipation	$P_D$	240	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.52	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Ambient <sup>1,2</sup>	$R_{\theta JA}$	53	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~+150	$^\circ\text{C}$

\* $E_{AS}$  test condition:  $V_{DD}= 10\text{V}$ ,  $R_G = 25\Omega$ ,  $L = 0.5\text{mH}$ , starting  $T_j = 25^\circ\text{C}$ .

**MOSFET ELECTRICAL CHARACTERISTICS ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Off Characteristics</b>						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	80			V
Zero gate voltage drain current	$I_{\text{DSS}}$	$V_{\text{DS}} = 80\text{V}, V_{\text{GS}} = 0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{\text{GSS}}$	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$			$\pm 100$	nA
<b>On Characteristics</b>						
Gate threshold voltage <sup>3</sup>	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 250\mu\text{A}$	2.0	3.0	4.0	V
Drain-source on-resistance <sup>3</sup>	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 20\text{A}$		4.0	5.0	$\text{m}\Omega$
<b>Dynamic characteristics</b>						
Input capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$		3300		pF
Output capacitance	$C_{\text{oss}}$			820		
Reverse transfer capacitance	$C_{\text{rss}}$			10		
<b>Switching Characteristics</b>						
Total gate charge	$Q_g$	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 70\text{A}$		49		nC
Gate-source charge	$Q_{\text{gs}}$			2		
Gate-drain charge	$Q_{\text{gd}}$			33		
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, V_{\text{DS}} = 40\text{V}$ $R_g = 4.7\Omega, I_{\text{D}} = 70\text{A}$		19		ns
Turn-on rise time	$t_r$			33		
Turn-off delay time	$t_{\text{d}(\text{off})}$			37		
Turn-off fall time	$t_f$			19		
<b>Diode Characteristics</b>						
Diode forward current	$I_s$				140	A
Diode pulsed forward current	$I_{\text{SM}}$				280	A
Diode forward voltage <sup>3</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 20\text{A}$			1.2	V

**Notes:**

1.  $R_{\theta\text{JA}}$  is measured with the device mounted on 1 in<sup>2</sup> FR4 board with 1oz. single side copper, in a still air environment with  $T_A = 25^\circ\text{C}$ .
2.  $R_{\theta\text{JA}}$  is measured in the steady state
3. Pulse test : Pulse width  $\leq 380\mu\text{s}$ , duty cycle  $\leq 2\%$ .

## Typical Electrical and Thermal Characteristics

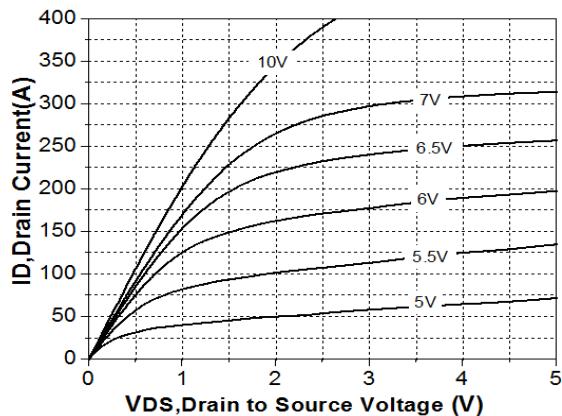


Figure1 Output Characteristics

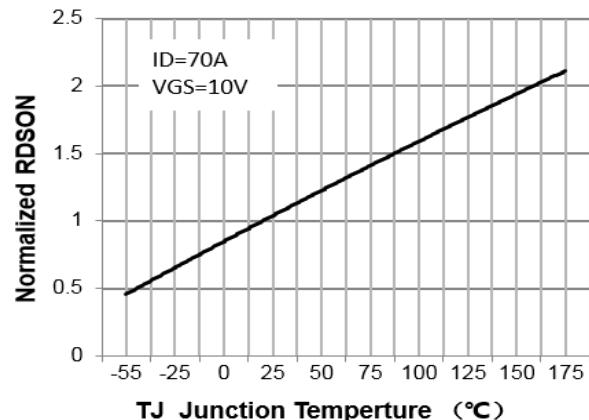


Figure4 Rdson - Junction Temperature

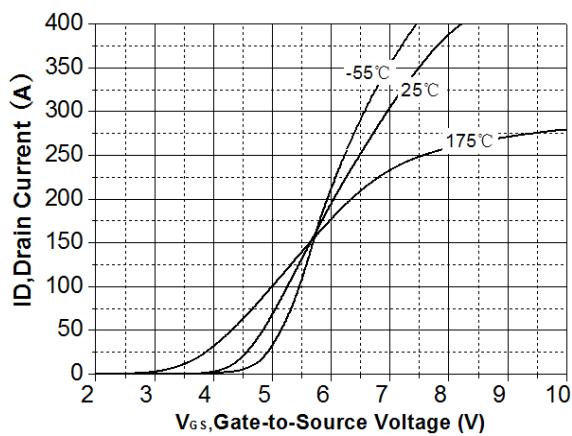


Figure2 Transfer Characteristics

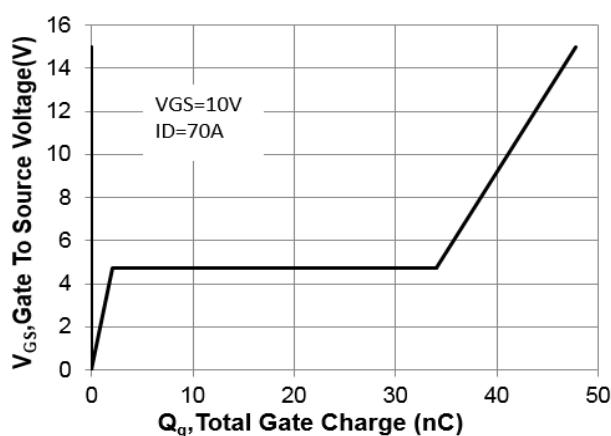


Figure5 Gate Charge

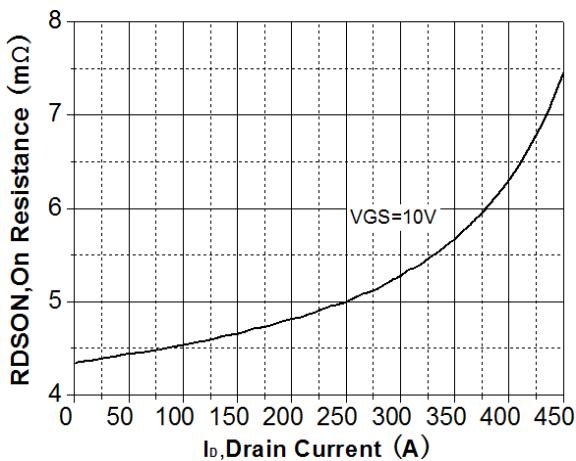


Figure3 Rdson - Drain Current

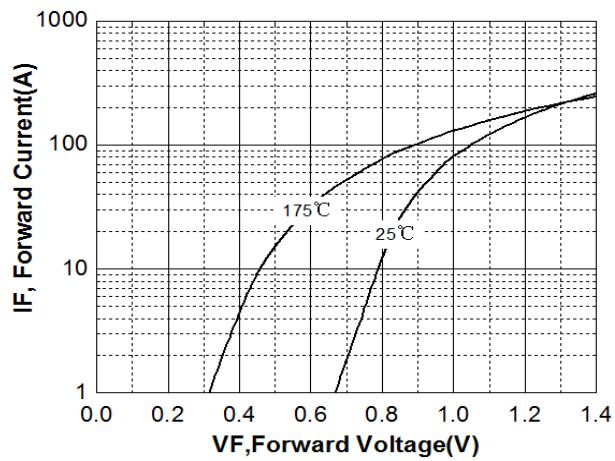


Figure6 Source - Drain Diode Forward

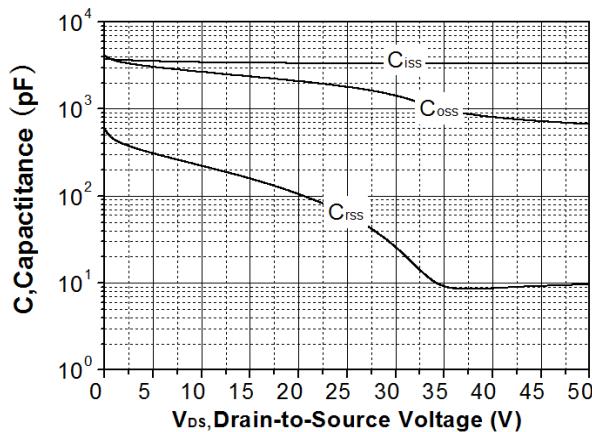


Figure 7 Capacitance vs Vds

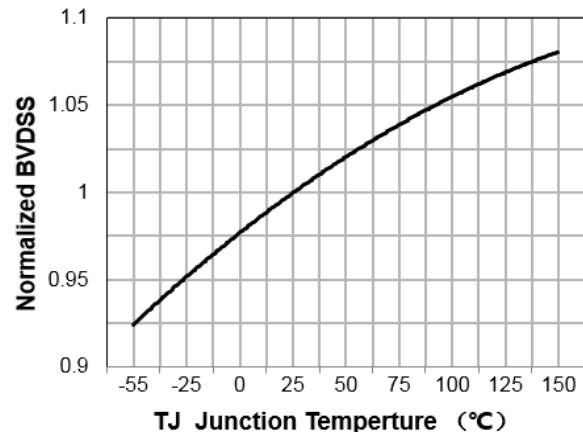


Figure 9 BV<sub>dss</sub> vs Junction Temperature

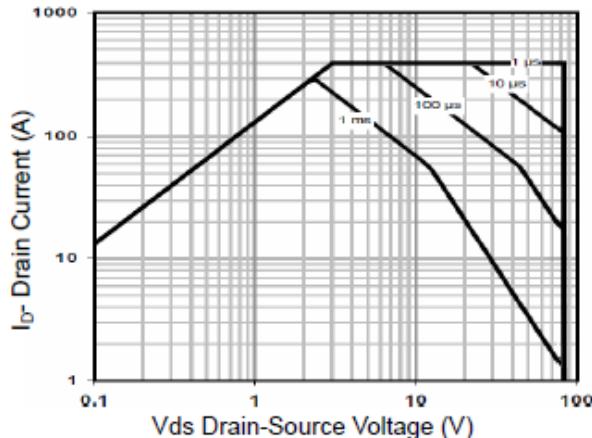


Figure 8 Safe Operation Area

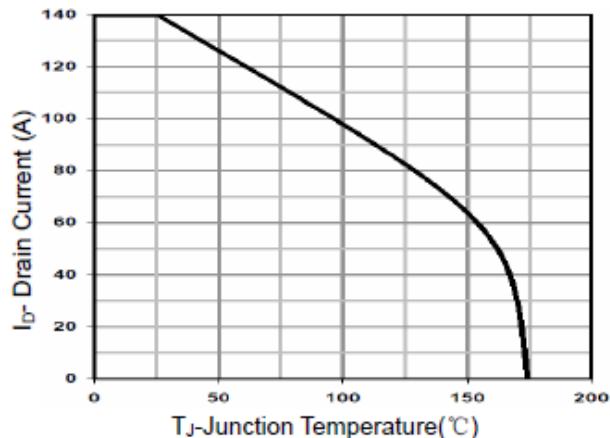


Figure 10 Current De-rating

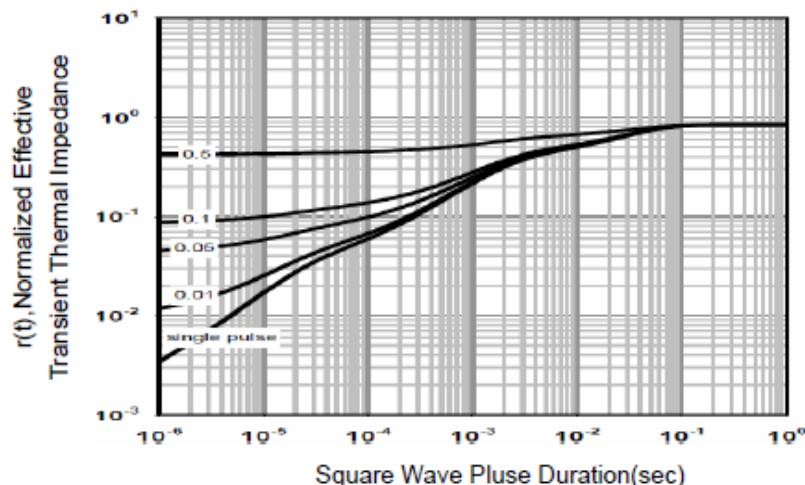
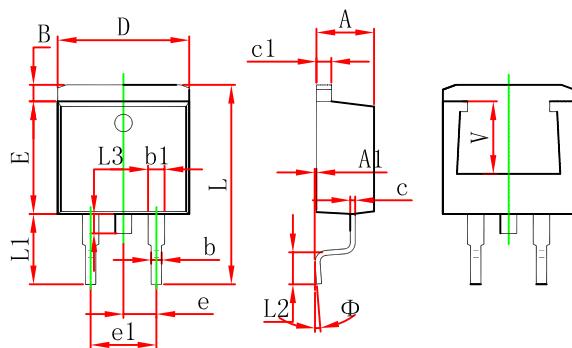


Figure 11 Normalized Maximum Transient Thermal Impedance

**TO-263-2L Package Information**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.470	4.670	0.176	0.184
A1	0.000	0.150	0.000	0.006
B	1.120	1.420	0.044	0.056
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
c	0.310	0.530	0.012	0.021
c1	1.170	1.370	0.046	0.054
D	10.010	10.310	0.394	0.406
E	8.500	8.900	0.335	0.350
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.196	0.204
L	14.940	15.500	0.588	0.610
L1	4.950	5.450	0.195	0.215
L2	2.340	2.740	0.092	0.108
L3	1.300	1.700	0.051	0.067
Φ	0°	8°	0°	8°
V	5.600 REF.		0.220REF.	